Liquid Cooling with iStarUSA's D-400 Chassis

iStarUSA has teamed up with CoolIT Systems to offer leading-edge liquid cooling technology in our D-400 chassis iStarUSA[°] Cool_{IT}



Heat, Disperse!

CoolIT's maintenance-free liquid cooling systems move thermal energy much more efficiently than air solutions do. CoolIT's direct contact liquid cooling technology transfers computer component heat more effectively by using patented copper split-flow micro-channel cold plates and low profile pump design. The CPU heat is transferred directly into the liquid and moved to the high-efficiency radiator where a fan cools things down.

Available for High Performance Systems

Liquid cooling has proven itself to be the standard in high performance desktop computing and that same performance is now available to the high performance computing server. This adds up to great value for system integrators. Through the increased ability to effectively dissipate heat, this chassis platform can accommodate much higher compute density and deliver the performance that the market needs. Now you can rely on a validated high performance Chassis/Thermal solution to support any AMD or Intel platform.



Introducing CoolIT Liquid Cooling Technology for Your iStarUSA Chassis

ECO III-120FB

IStarUSA COOLT overed by Startist' Group

Using a 120 x 45mm radiator along with a 120 x 38mm fan of 4000 RPM max while installed into the D-400 4U Server Rackmount Chassis, the thermal performance was able to achieve 0.080 C/W at 170W load. More information can be obtained through iStarUSA and CoolIT.



Heat Exchanger (HEX/Radiator) ECO II Head Unit with Pump & Cold Plate

How the ECO Sealed System Works

General Specifications	
Model	ECO III-120FB
Part Number	900-00191
Description	120mm Class Liquid Cooling Solution
Thermal Resistance	~0.080 $^\circ\text{C/W}$ (with default fan at maximum speed)
FHE Base	Copper Micro-channel
Tubing	Flexible corrugated FEP 8mm OD, 6mm ID
Tubing Length	~ 280 mm
Coolant	Low toxicity propylene glycol/water mixture with anticorrosion/antifungal package
Thermal Interface Materials	Dow Corning TC-5026
Total Weight	725g (w/o fan)

Pump Specifications		
Pump Motor	Electronically commutated, brushless DC	
Nominal Voltage	12 VDC	
Nominal Current	0.12 A	
Power	1.44 W	
Typical Flow Rate	0.94 L/min	
Speed	2150 RPM +/- 10%	
Environmental Specifications		

Operating Range Storage Range	Operating Range	Temperature (0 °C ~ 50 °C)
		Humidity (35% ~ 85%)
	Storege Denge	Temperature (-40 °C ~ 85 °C)
	Humidity (35% ~ 85%)	

External Dimensions (LCS)*





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